

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Kuo-Shu Kao</td> <td>03/20/2013</td> </tr> <tr> <td>Tao-Chih Chang</td> <td>03/20/2013</td> </tr> <tr> <td>Wen-Chih Chen</td> <td>03/20/2013</td> </tr> </tbody> </table>		Name	Execution Date	Kuo-Shu Kao	03/20/2013	Tao-Chih Chang	03/20/2013	Wen-Chih Chen	03/20/2013
Name	Execution Date								
Kuo-Shu Kao	03/20/2013								
Tao-Chih Chang	03/20/2013								
Wen-Chih Chen	03/20/2013								
RECEIVING PARTY DATA									
Name:	Industrial Technology Research Institute								
Street Address:	No. 195, Sec. 4, Chung Hsing Rd., Chutung,								
City:	Hsinchu								
State/Country:	TAIWAN								
Postal Code:	31040								
PROPERTY NUMBERS Total: 1									
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13855719</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13855719				
Property Type	Number								
Application Number:	13855719								
CORRESPONDENCE DATA									
Fax Number:	5105807280								
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>									
Email:	usa@jcipgroup.com.tw								
Correspondent Name:	Jianq Chyun Intellectual Property Office								
Address Line 1:	7F.-1, NO. 100, ROOSEVELT RD., SEC. 2,								
Address Line 4:	Taipei, TAIWAN 100								
ATTORNEY DOCKET NUMBER:	43177-US-PA								
NAME OF SUBMITTER:	Belinda Lee								
Signature:	/Belinda Lee/								
Date:	04/08/2013								
Total Attachments: 2 source=43177_assgn#page1.tif source=43177_assgn#page2.tif									

CH \$40.00 13855719

P51010057US
43177-US-PA

ASSIGNMENT

WHEREAS,

- 1. Kuo-Shu Kao
- 2. Tao-Chih Chang
- 3. Wen-Chih Chen

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **SOLDER, SOLDER JOINT STRUCTURE AND METHOD OF FORMING SOLDER JOINT STRUCTURE**

Filed: Serial No.

Executed concurrently with the execution of this instrument

WHEREAS, Industrial Technology Research Institute
of No. 195, Sec. 4, Chung Hsing Rd., Chutung, Hsinchu 31040, Taiwan, R. O. C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said rights, title and interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

P51010057US
43177-US-PA

ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: Kuo-Shu Kao Date: 2013.03.20
Sole or First Joint Inventor: Kuo-Shu Kao

Signature: Tao-Chih Chang Date: 2013.03.20
Second Joint Inventor (if any): Tao-Chih Chang

Signature: Wen-Chih Chen Date: 2013.03.20
Third Joint Inventor (if any): Wen-Chih Chen